

> Mechanical Specification:

(1) Dimension

- Chip size: 25 mil x 29 mil ($645 \pm 25 \mu\text{m} \times 745 \pm 25 \mu\text{m}$)
- Thickness: 5.5 mil ($140 \pm 10 \mu\text{m}$)
- P bonding pad: 3.5 mil ($90 \pm 10 \mu\text{m}$)
- N bonding pad: 3.5 mil ($90 \pm 10 \mu\text{m}$)

(2) Metallization

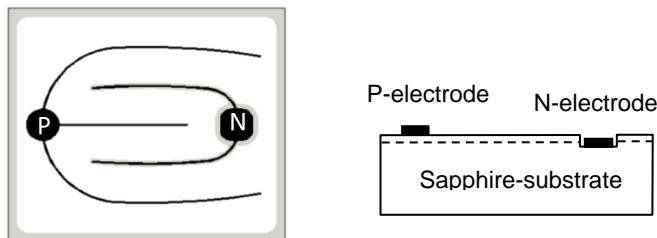
- Topside P electrode: Au alloy
- Topside N electrode: Au alloy

Features:

- High radiant flux
- Long operation life
- Lambertian radiation

Applications:

- Commercial Lighting



> Electro-optical Characteristics at 25°C: ⁽¹⁾

| Parameter | Symbol | Condition | Min. | Typ. | Max. | Unit |
|--------------------------------------|-----------------|------------|------------|------|------|------|
| Forward Voltage | Vf1 | If = 10uA | 1.6 | - | - | V |
| | Vf | If = 120mA | - | 3.2 | 3.4 | V |
| Peak Wavelength⁽²⁾ | λ_p | If = 120mA | 400 | - | 415 | nm |
| Spectra Half-width | $\Delta\lambda$ | If = 120mA | - | 15 | - | nm |
| Radiant Flux⁽³⁾⁽⁴⁾ | Po | A69 | If = 120mA | 200 | - | 210 |
| | | A70 | | 210 | - | 220 |
| | | A71 | | 220 | - | 230 |
| | | A72 | | 230 | - | 240 |

Note:

(1) ESD protection during chip handling is recommended.

(2) Basically, the wavelength span is 15nm; however, customers' special requirements are also welcome.

(3) Radiant flux is determined by using an Ag-plated TO-can header without an encapsulant.

(4) Radiant flux measurement allows a tolerance of $\pm 15\%$.

> Absolute Maximum Ratings:

| Parameter | Symbol | Condition | Rating | Unit |
|------------------------------|------------------|-----------------------------|-------------|------|
| Forward DC Current | If | T _a = 25°C | ≤ 240 | mA |
| Junction Temperature | T _j | - | ≤ 125 | °C |
| Storage Temperature | T _{stg} | Chip | -40 ~ +85 | °C |
| | | Chip-on-tape/storage | 5 ~ 35 | °C |
| | | Chip-on-tape/transportation | -20 ~ +65 | °C |
| Temperature during Packaging | - | - | 280(<10sec) | °C |

Note: Maximum ratings are package dependent. The above maximum ratings were determined using a Printed Circuit Board (PCB) without an encapsulant. Stresses in excess of the absolute maximum ratings such as forward current and junction temperature may cause damage to the LED.

> Characteristic Curves:

Fig.1 – Relative luminous Intensity vs. Forward Current

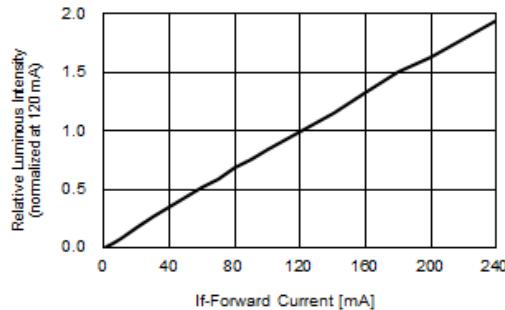


Fig.2 – Forward Current vs. Forward Voltage

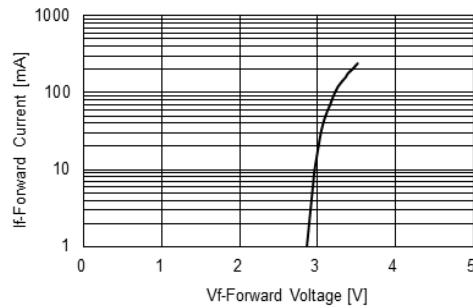


Fig.3 – Relative Intensity (@120mA) vs. Ambient Temperature

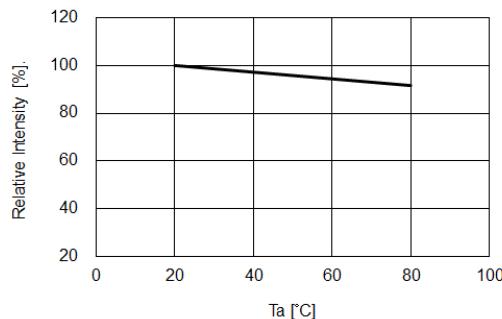


Fig.4 – Forward Voltage (@120mA) vs. Ambient Temperature

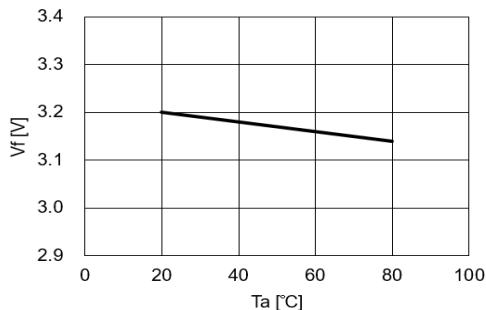


Fig.5 – Peak Wavelength (@120mA) vs. Ambient Temperature

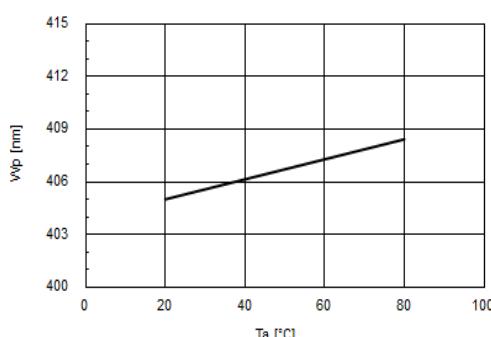


Fig.6 – Maximum Driving Forward DC Current vs. Ambient Temperature (De-rating based on T_j max. = 125°C)

